

ABSTRACT

Provided is a structure in which a shield 308 and a heat sink 307 integrated with a radiation fin 306 are sandwiched by a main substrate 381a and a power source substrate 381b. A hood 142d covers the radiation fin 306 so as to collect air for cooling. Major parts of the main substrate 381a are in contact with the heat sink 307 via heat conduction members having different heat conductivity so that an even thermal distribution is provided. Thus, parts of electronic equipment can be efficiently disposed in a limited space. Moreover, the parts of the electronic equipment can be effectively cooled.